



Intel Roadmap Overview

Sept 22nd, 2009

Stephen L. Smith

Vice President, Director of Operations

Intel Architecture Group

Contact George Alfs with any questions

Agenda

- **Server Roadmap**
- Client Roadmap
- Netbook / Nettop Roadmap

Tick-Tock Development Model: *Sustained Microprocessor Leadership*

Tick

Tock

Tick

Tock

Tick

Tock

Tick

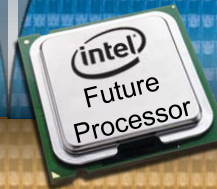
Tock

65nm

45nm

32nm

22nm

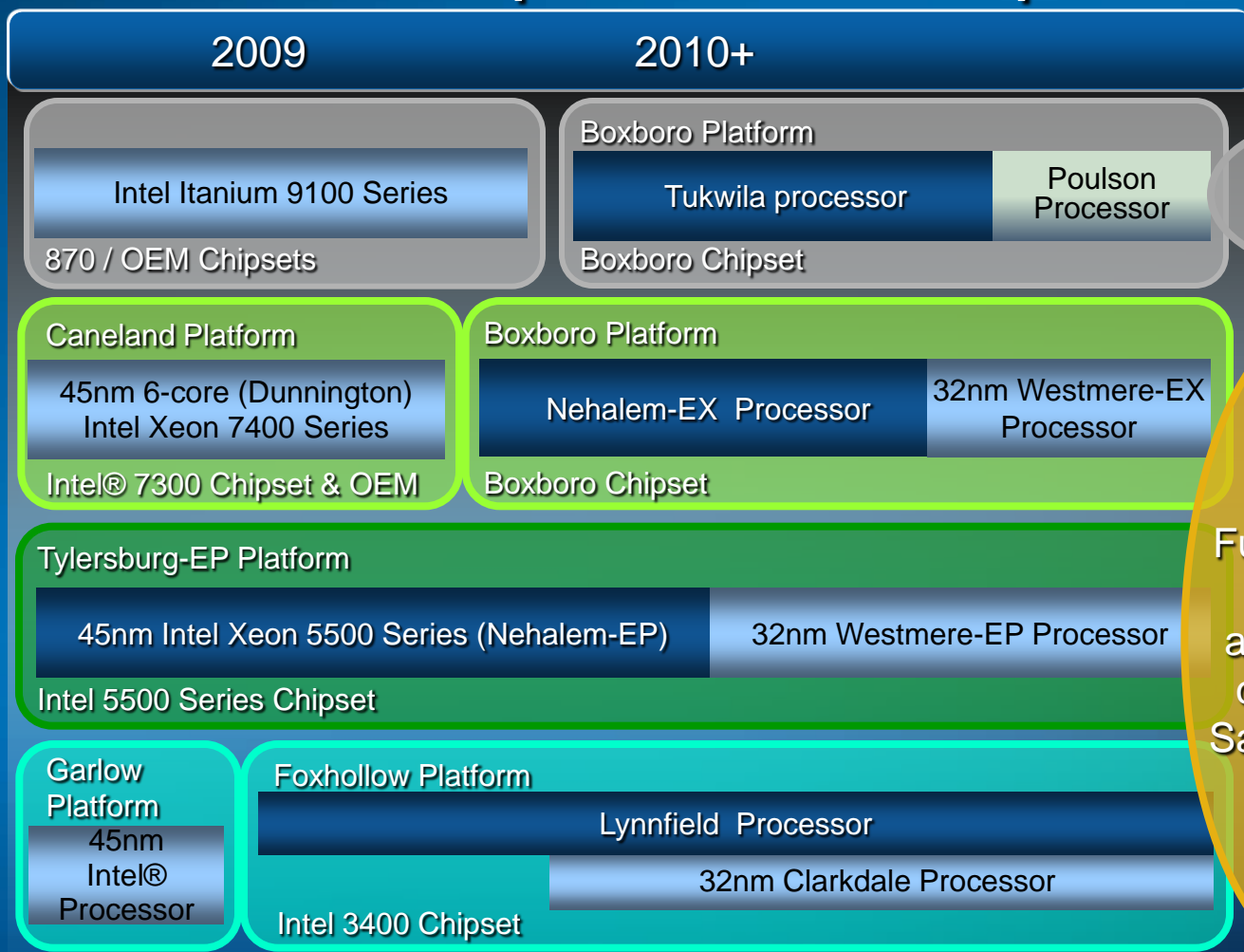


Intel® Core™
Microarchitecture

Nehalem
Microarchitecture

Sandy Bridge
Microarchitecture

Intel® Enterprise Roadmap



Future Kittson Processor

Future Intel® micro-architecture codename Sandy Bridge

32nm Upgrades Across All Intel® Segments

intel
Itanium
inside

Mission Critical
9000 Sequence

intel
Xeon
inside

Expandable
7000 Sequence

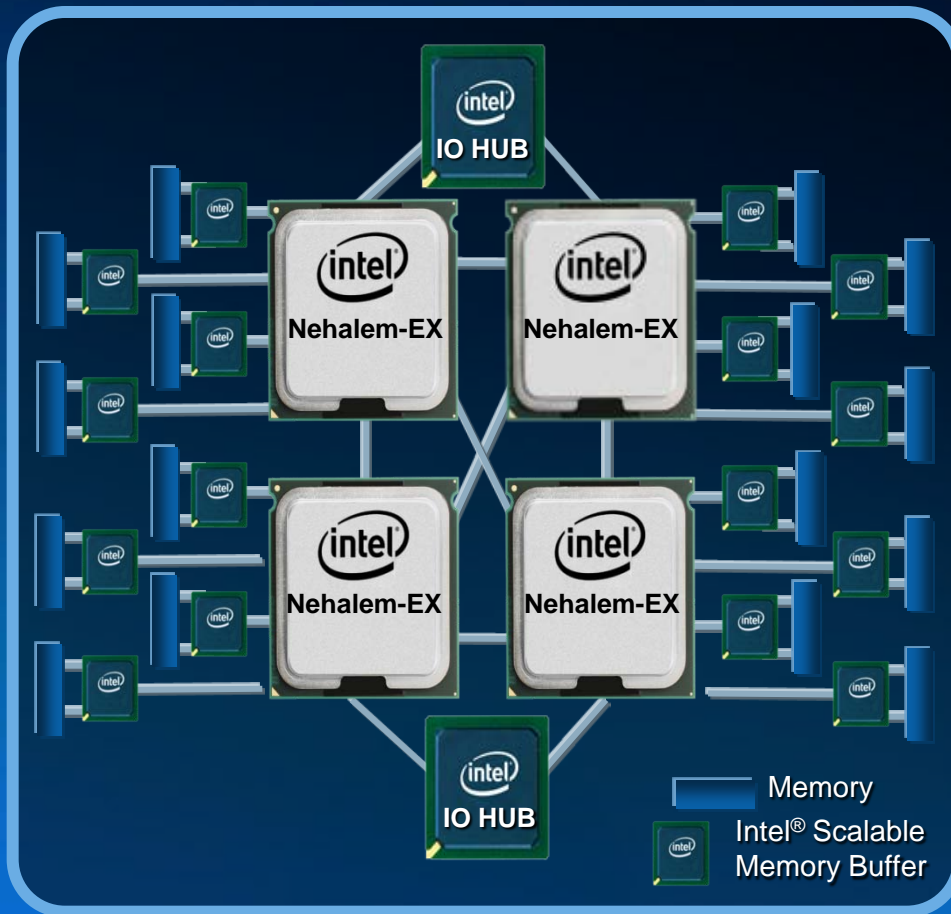
intel
Xeon
inside

Efficient Performance
5000 Sequence

intel
Xeon
inside

Entry
3000 Sequence

Nehalem-EX: 4-Socket Platform



- 8 cores per processor
- 64 threads
- Intel® Scalable Memory Interconnect with Buffers
 - Up to 1 TB memory support (4S)
- Scalable to 8+ sockets with OEM node controllers

Enterprise, Virtualization, and HPC Leadership

Nehalem-based Server Performance

The Greatest Intel® Xeon® Performance Leap In History!

Xeon® 5500 vs. Xeon® 5400 *(Nehalem-EP) (Harpertown)*

Up to **3.5x** Memory Bandwidth
Up to **2.5x** Database Performance
Up to **1.7x** Integer Throughput
Up to **2.2x** Floating Point Throughput

Nehalem-EX vs. Xeon® 7400 *(Dunnington)*

Up to **9x** Memory Bandwidth¹
Up to **3x** Database Performance²
> 1.7x Integer Throughput
> 2.2x Floating Point Throughput

Expecting larger gains from Nehalem Architecture in EX

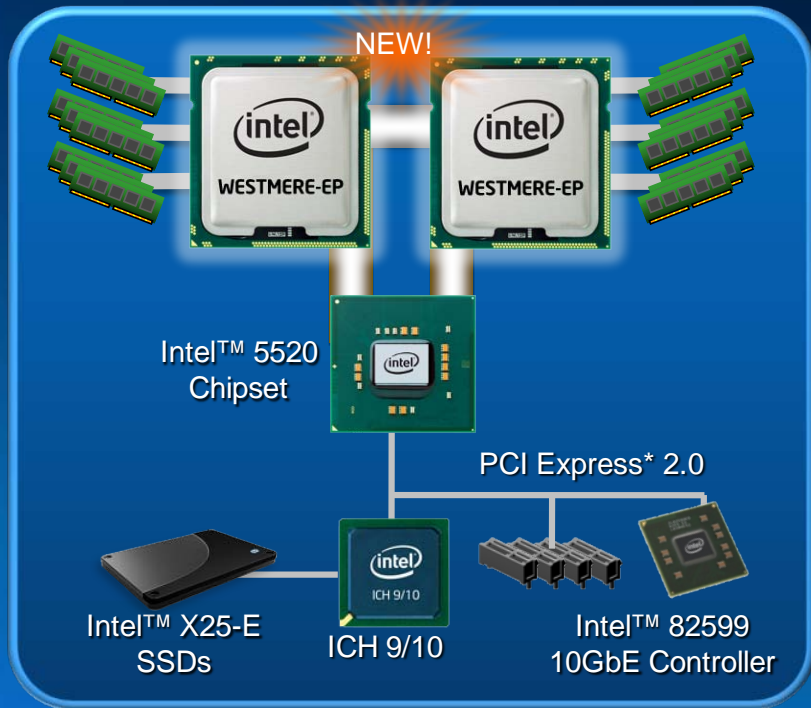
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¹Based on May'09 internal measurement using Intel internal workload

²3x Performance vs. Prior Generation based on Intel internal measurements on an internal OLTP workload comparing 4S Nehalem-EX to 4S Intel® Xeon® X7460 ("Caneland" platform).

Source: Intel. December 8, 2008. Based on Internal testing on pre-production Intel Xeon Processor 5500 based servers. Performance Gains Represent A Blend (GEO Mean) Of Five Common 2-socket Workload Types Across A Range Of Typical Usages

Westmere-EP: Next Generation Xeon® Processor



- Significant compute performance increase at the same power*
- Enhanced security
 - TXT for hardened virtualization
 - AES to broaden encryption usage**



Socket Compatible with Intel® Xeon® 5500 Platform

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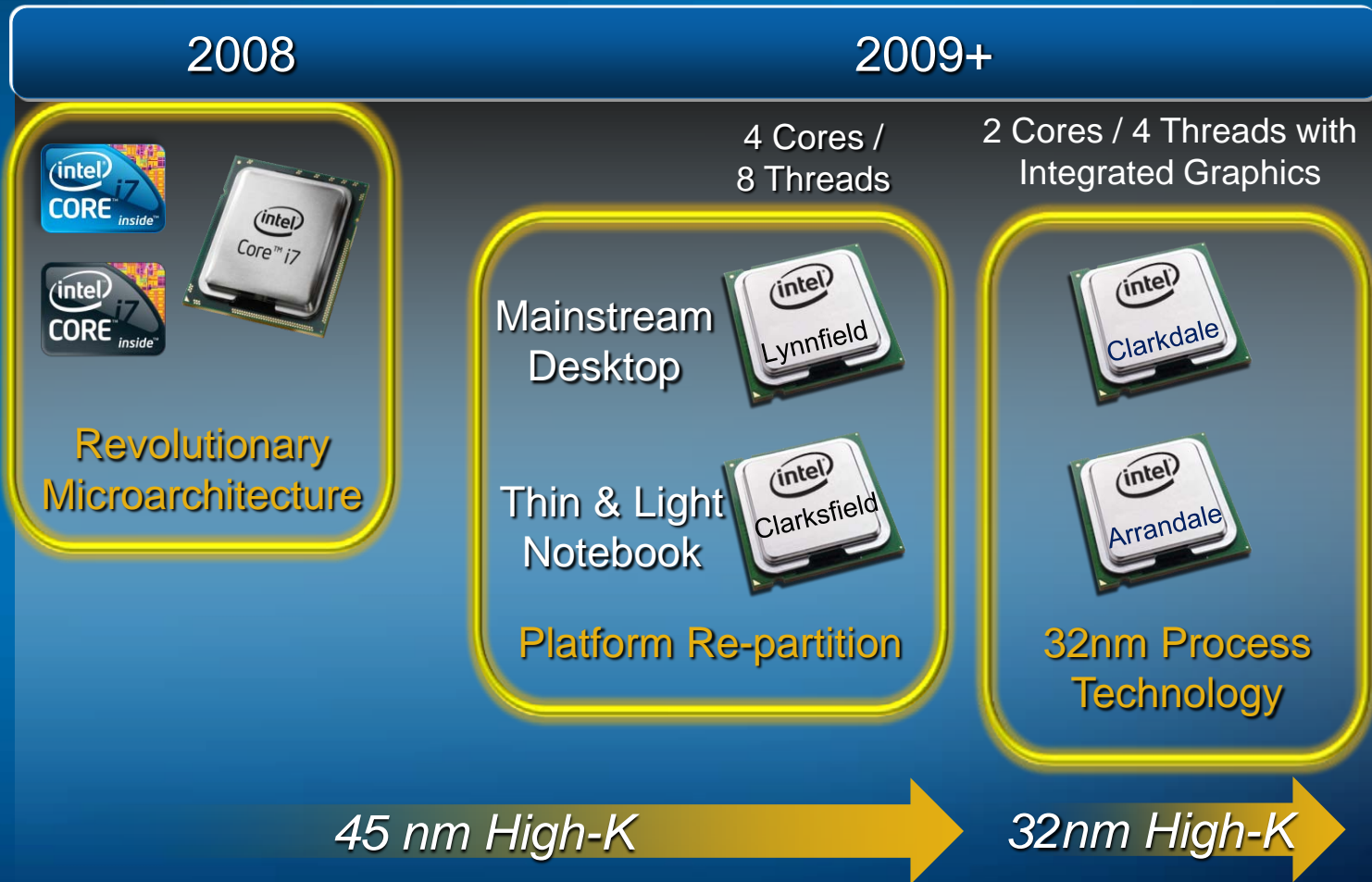
*Intel internal estimate of integer measurements comparing Westmere-EP reference system and Nehalem-EP system

**Intel internal measurements based on 140Kb standard banking transaction comparison between Westmere-EP CPU with and without AES-NI acceleration.

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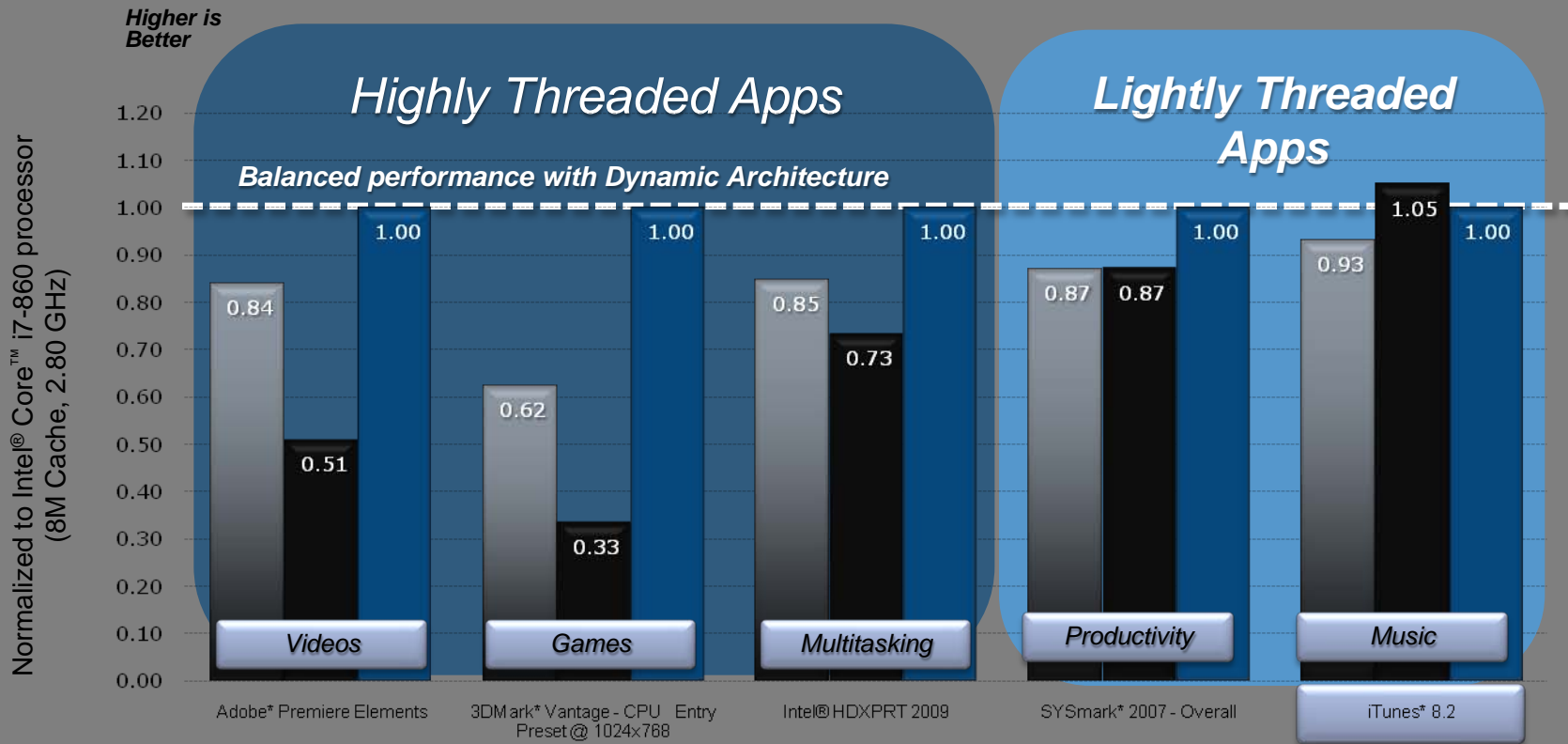
Enabling Nehalem For Every Segment



Get the Best of Both Worlds with the new Intel® Core™ i7 processor



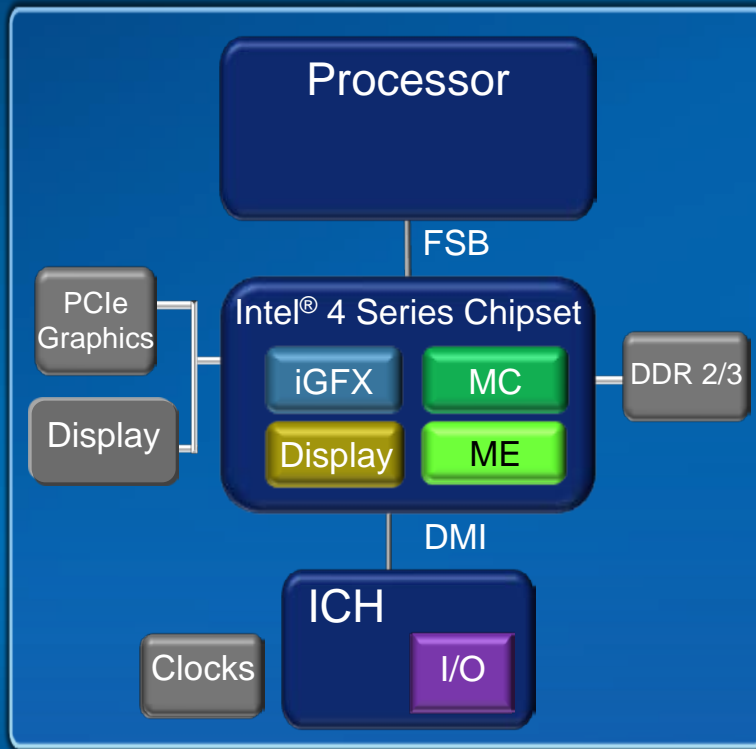
- Intel® Core™ 2 Quad processor Q9650 (12M Cache, 3.00 GHz, 1333 MHz FSB)
- Intel® Core™ 2 Duo processor E8600 (6M Cache, 3.33 GHz, 1333 MHz FSB)
- Intel® Core™ i7-860 processor (8M Cache, 2.80 GHz)



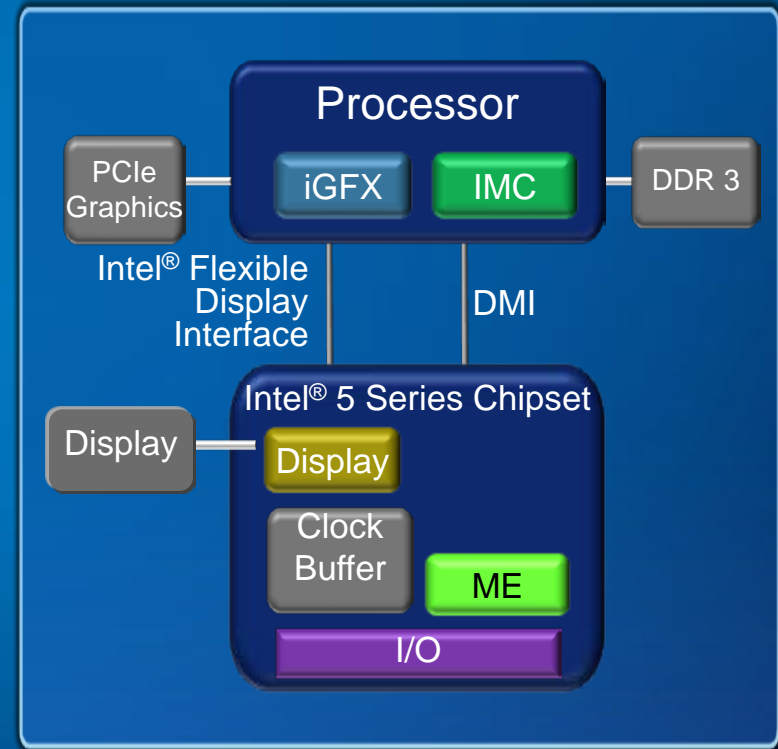
Accelerate Everything!

Mainstream Client Platform Repartitioning

Penryn based
3-Chip Solution

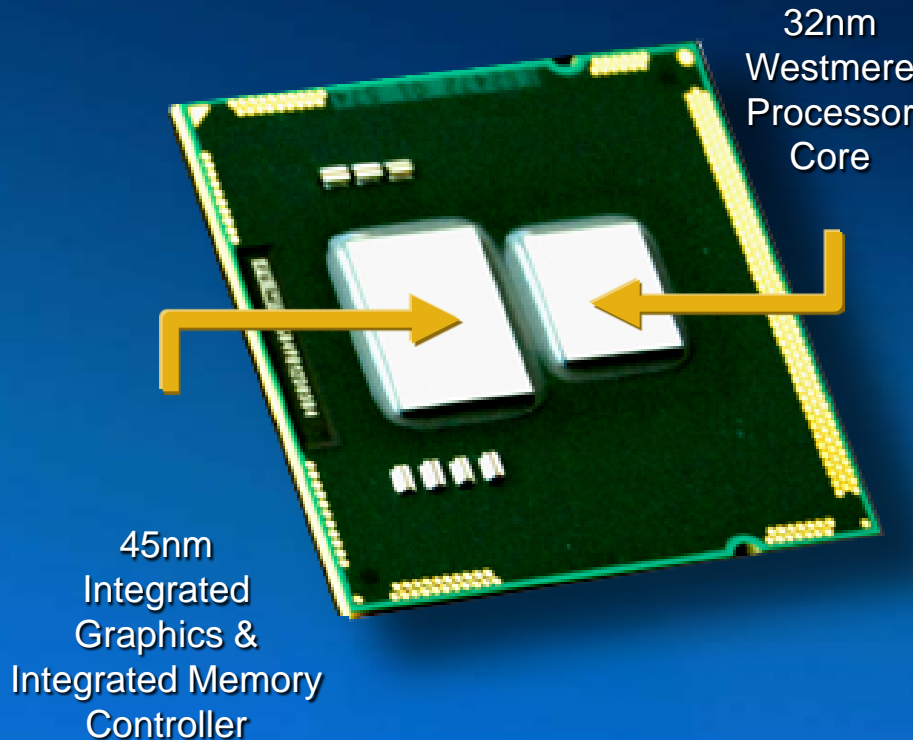


Westmere based
2-Chip Solution



*Repartitioning of the Client Platform
Greater Performance and Lower Power via Higher Integration*

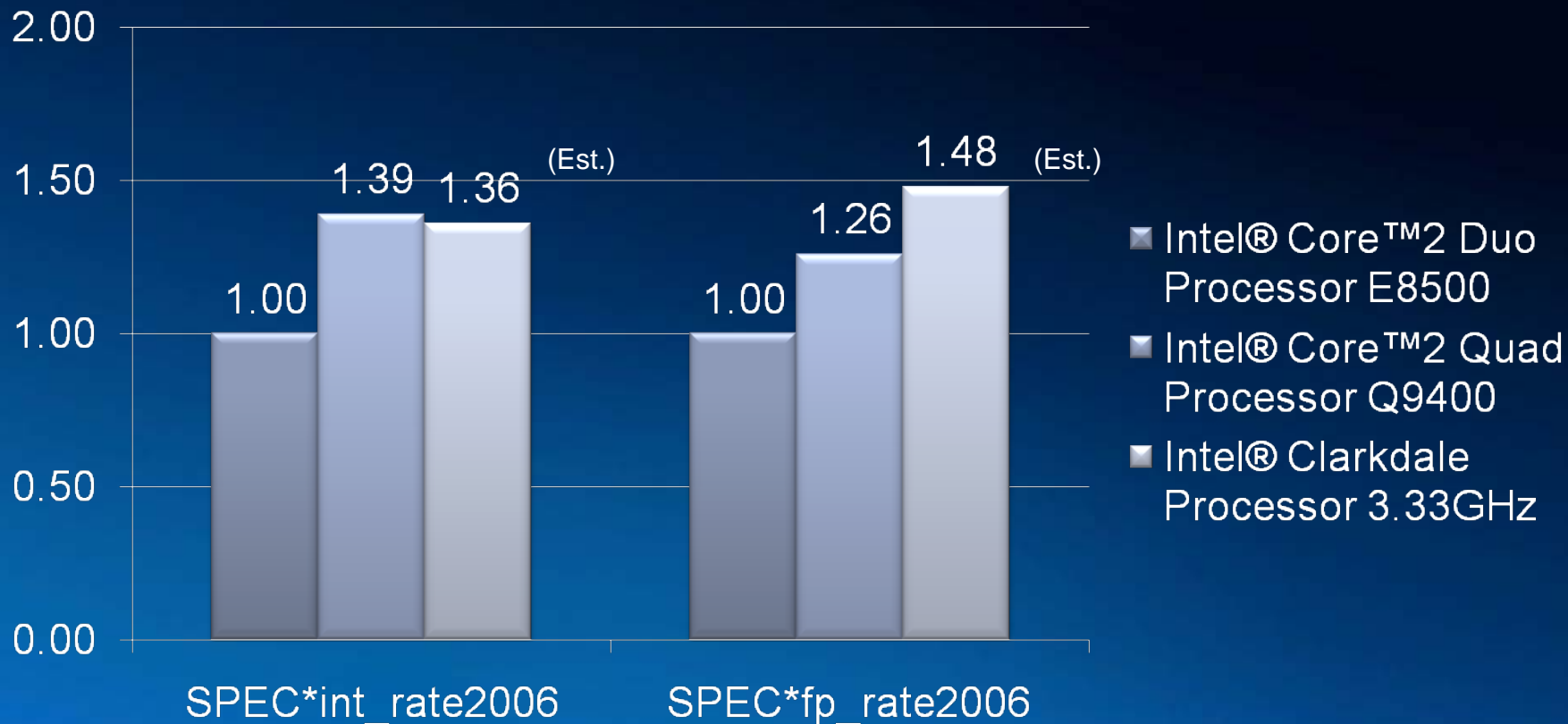
First 32nm Westmere Products



Key Features

- Intel® Turbo Boost Technology
- Intel® Hyper-Threading Technology
- Intel® Graphics Media Accelerator
- Integrated Memory Controller with 2 Channel DDR3

SPEC* CPU2006



Intel® Clarkdale Processors: Major Performance Advances for desktop PCs

SPEC, SPECint, SPECfp, SPECrate are trademarks of the Standard Performance Evaluation Corporation. For more information go to: www.spec.org/spec/trademarks.html.

Source: Intel. Estimate based on pre-production Clarkdale processor (3.33GHz/4MB), 4GB (2x2GB) Dual channel DDR3-1333, 7200 rpm HDD. Measured results based on Intel® Core™ 2 Duo E8500 3.16GHz/1333MHz FSB/6MB and Intel® Core™ 2 Quad Q9400 2.66GHz/1333MHz FSB/6MB: Intel DG45ID, Kingston* 4GB (2x2GB) Dual channel DDR2 800 5-5-5-18, Seagate* 1TB HDD, X4500HD with 8.15.10.1840 BIOS: IDG4510H.86A.1357, Intel INF 9.1.1.1015)

Graphics Capability Roadmap: 2009-2011

- Expand the Processor value proposition with new media, 3D and power management technologies that scale with our process technology and tick tock cadence

- Small form factors
- Power savings
- Media functionality
- 3D standards



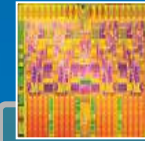
**G45
GM45**

- Full HD/Bluray support
- DX10, WDDM1.1 Graphics
- Advanced Mobile power saving technologies



**Clarkdale
Arrandale**

- + Intel® Clear Video HD Technology with dual HD stream support
- + Premium Audio
- + Graphics Turbo¹



**Sandy
Bridge**

- + Next gen Intel® Clear Video HD Technology
- + Graphics Turbo+

1. Feature only available on the mobile version

Extending Performance Leadership for Enthusiasts

2008

2010

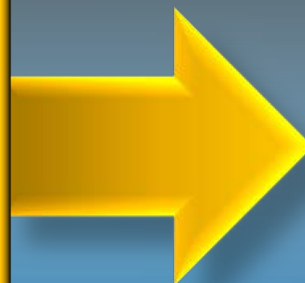
High
End
Desktop



4 Cores
8 Threads

Revolutionary
Microarchitecture

45nm High-K



6 Cores
12 Threads

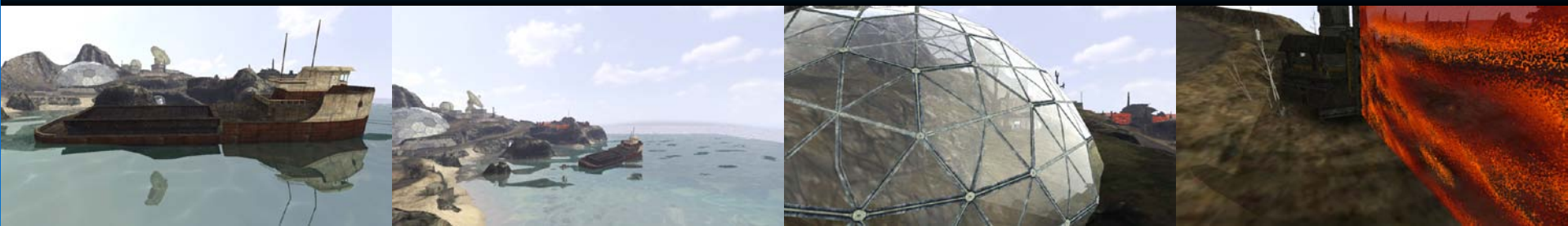
Compatible with Intel®
X58 Express Chipset

32nm High-K

6-Core Gulftown Platform Coming in 2010

Larrabee Execution Update

- First products: discrete performance graphics
- Software development vehicle shipping now
- Enemy territory: Quake Wars, id Software



Different Devices for Different Uses



Ultra-thin Laptop

- Premium offering spanning consumer price pts
- 0.8-1.0" high, ≥ 11.6 " screens
- Thin & light for Increased mobility
- Multitasking performance & rich internet experience
- Content Creation/Editing



Mainstream Laptop

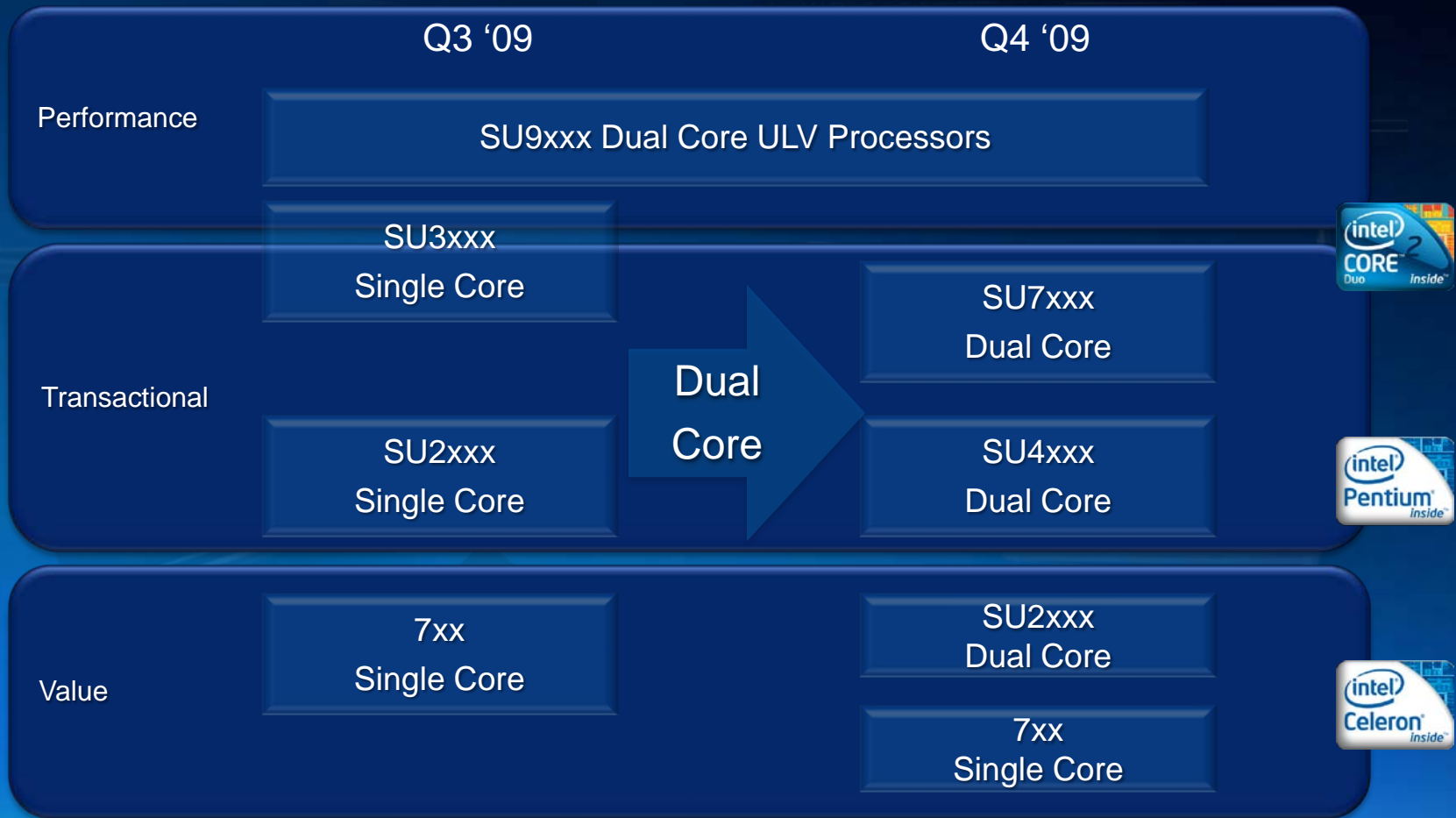
- Great performance for entertainment, productivity, and rich web experience
- Content creation and Intense workloads
- Range of form factors



Netbook

- ≤ 10.2 " screens
- Purpose-built for Internet use
- Learn, Communicate, View
- Content consumption

Momentum Continues With Transition to Intel® Dual Core Processors for Ultra-Thin Laptops!



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- **Netbook / Nettop Roadmap**

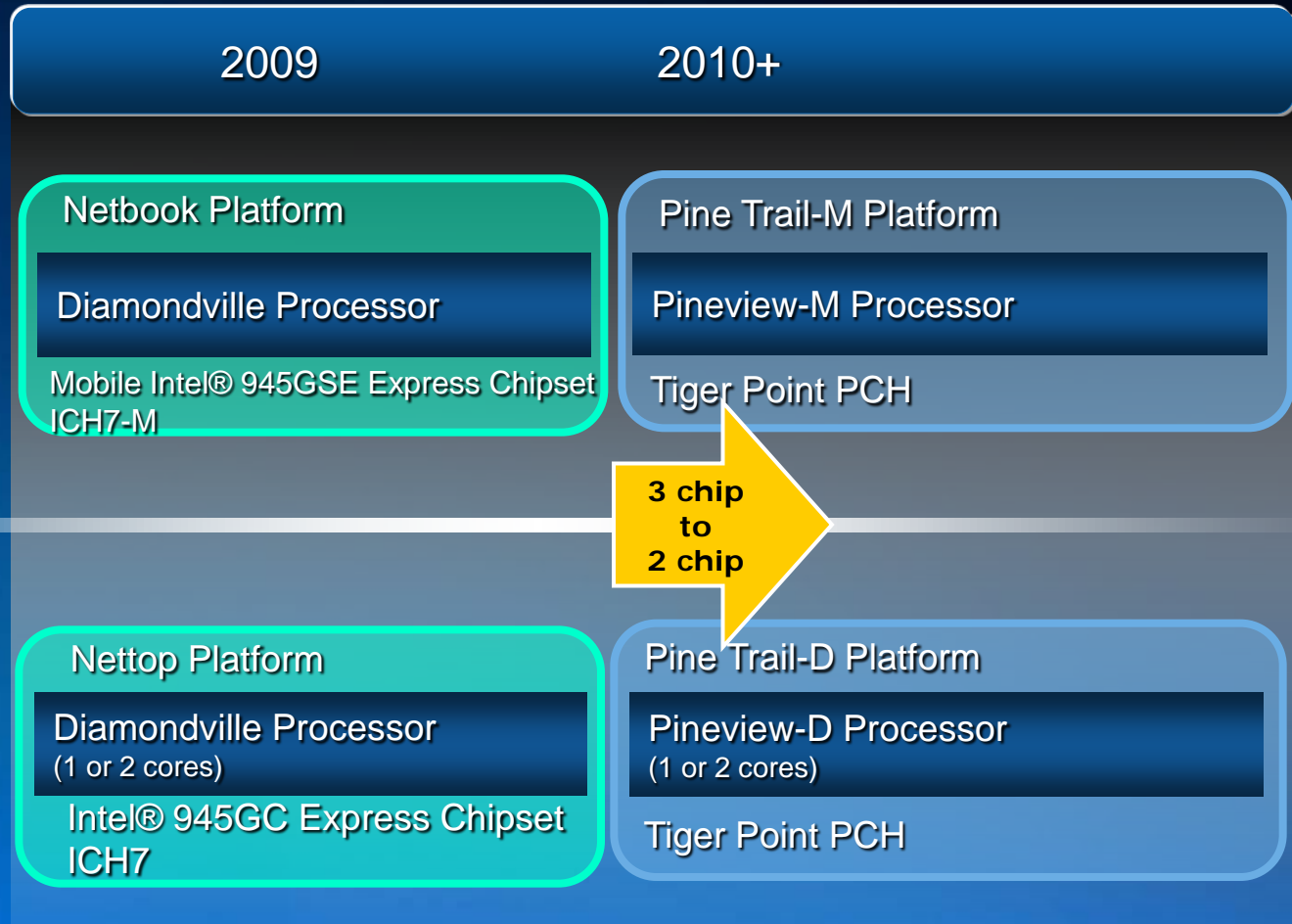
Netbook / Nettop Roadmap



Netbooks



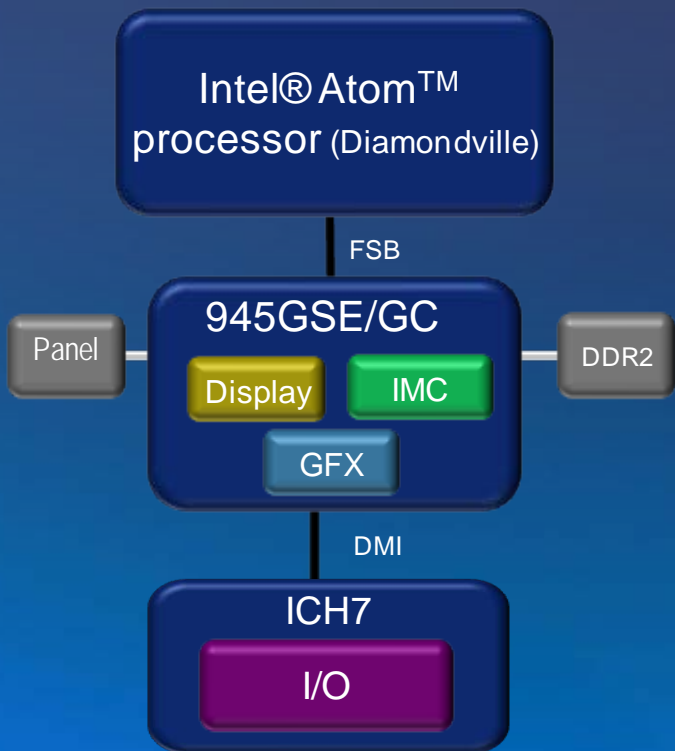
Nettops



Purpose built solutions to enable netbooks and nettops for the internet and basic computing

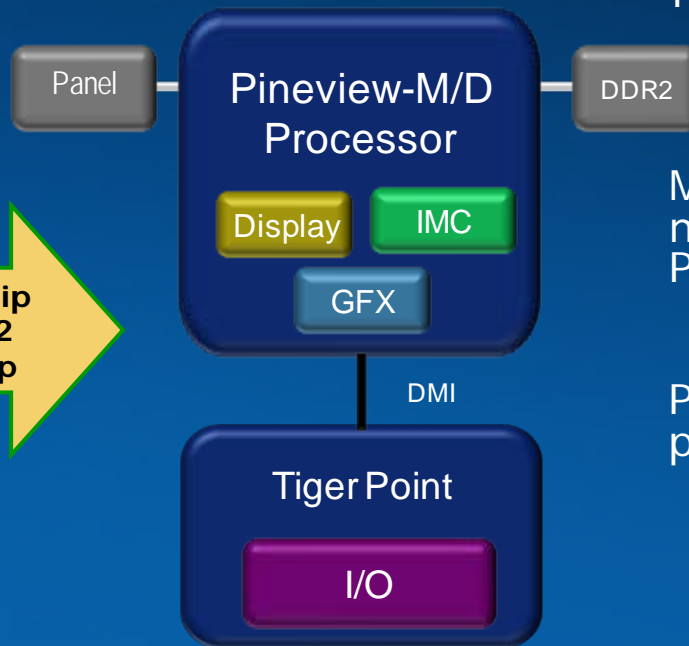
Pine Trail: Second Generation Net* Platform

Net* Platform'08



3 chip
to 2
chip

Pine Trail



Graphics/display
move into
Processor

Memory Controller
moves into
Processor

Package area and
power savings

Integration offers platform BOM savings, power reduction, and improved performance

Summary

- Intel executing to tick-tock CPU roadmap
- 32 nm Westmere processors deliver higher integration and energy efficient performance
- Turbo Technology in Westmere is a breakthrough in multicore dynamic design
- Ultra-Thin laptop momentum continues to build with new dual-core processor lineup

Risk Factors

The above statements and any others in this document that refer to plans and expectations for the third quarter, the year and the future are forward-looking statements that involve a number of risks and uncertainties. Many factors could affect Intel's actual results, and variances from Intel's current expectations regarding such factors could cause actual results to differ materially from those expressed in these forward-looking statements. Intel presently considers the following to be the important factors that could cause actual results to differ materially from the corporation's expectations. Ongoing uncertainty in global economic conditions pose a risk to the overall economy as consumers and businesses may defer purchases in response to tighter credit and negative financial news, which could negatively affect product demand and other related matters. Consequently, demand could be different from Intel's expectations due to factors including changes in business and economic conditions, including conditions in the credit market that could affect consumer confidence; customer acceptance of Intel's and competitors' products; changes in customer order patterns including order cancellations; and changes in the level of inventory at customers. Intel operates in intensely competitive industries that are characterized by a high percentage of costs that are fixed or difficult to reduce in the short term and product demand that is highly variable and difficult to forecast. Additionally, Intel is in the process of transitioning to its next generation of products on 32nm process technology, and there could be execution issues associated with these changes, including product defects and errata along with lower than anticipated manufacturing yields. Revenue and the gross margin percentage are affected by the timing of new Intel product introductions and the demand for and market acceptance of Intel's products; actions taken by Intel's competitors, including product offerings and introductions, marketing programs and pricing pressures and Intel's response to such actions; and Intel's ability to respond quickly to technological developments and to incorporate new features into its products. The gross margin percentage could vary significantly from expectations based on changes in revenue levels; capacity utilization; start-up costs, including costs associated with the new 32nm process technology; variations in inventory valuation, including variations related to the timing of qualifying products for sale; excess or obsolete inventory; product mix and pricing; manufacturing yields; changes in unit costs; impairments of long-lived assets, including manufacturing, assembly/test and intangible assets; and the timing and execution of the manufacturing ramp and associated costs. Expenses, particularly certain marketing and compensation expenses, as well as restructuring and asset impairment charges, vary depending on the level of demand for Intel's products and the level of revenue and profits. The current financial stress affecting the banking system and financial markets and the going concern threats to investment banks and other financial institutions have resulted in a tightening in the credit markets, a reduced level of liquidity in many financial markets, and heightened volatility in fixed income, credit and equity markets. There could be a number of follow-on effects from the credit crisis on Intel's business, including insolvency of key suppliers resulting in product delays; inability of customers to obtain credit to finance purchases of our products and/or customer insolvencies; counterparty failures negatively impacting our treasury operations; increased expense or inability to obtain short-term financing of Intel's operations from the issuance of commercial paper; and increased impairments from the inability of investee companies to obtain financing. 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Intel® Turbo Boost Technology requires a PC with a processor with Intel Turbo Boost Technology capability. Intel Turbo Boost Technology performance varies depending on hardware, software and overall system configuration. Check with your PC manufacturer on whether your system delivers Intel Turbo Boost Technology. For more information, see <http://www.intel.com/technology/turboboost>.

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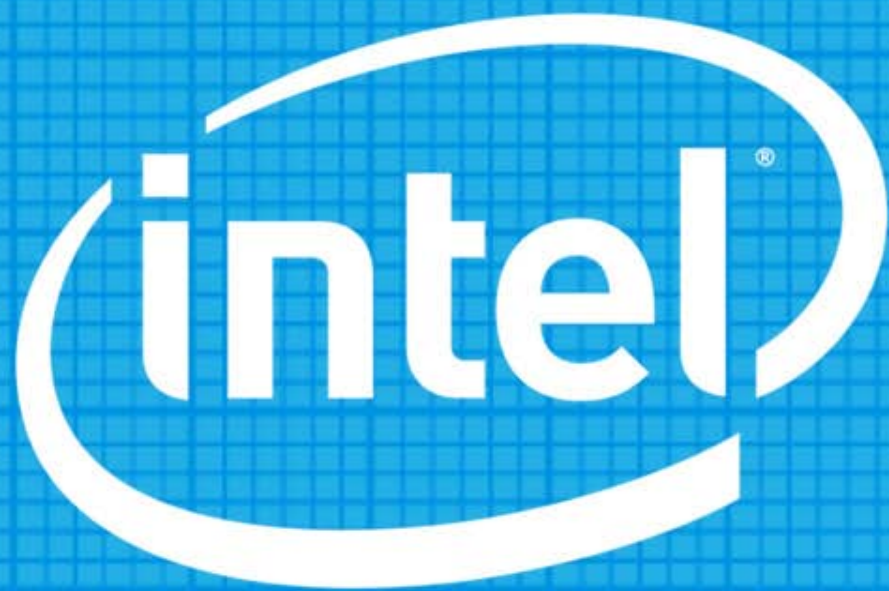
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Nehalem and Westmere Decoder Ring

	Segment	Nehalem (45nm)	Westmere (32nm)
Desktop	High-End	Bloomfield (4C / 8T)	Gulftown (6C / 12T)
	Mainstream	Lynnfield (4C / 8T)	Clarkdale (2C / 4T + iGFX)
Mobile		Clarksfield (4C / 8T)	Arrandale (2C / 4T + iGFX)
Server	Expandable Scalable (typically 4+ sockets)	Nehalem-EX (8C / 16T)	Westmere-EX
	Efficient Performance (typically 2 sockets)	Nehalem-EP(4C / 8T)	Westmere-EP (6C / 12T)
	Entry (EN) (typically 1 socket)	Lynnfield (4C / 8T)	Clarkdale (2C / 4T + iGFX)*

* Client branded product supported for servers

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Desktop Configurations – Intel® processors codename Lynnfield



Configuration 1: Intel® Core™ i7-870 processor (2.93GHz, 4C/8T, 8MB Cache, IMC, DDR3-1333) on Intel® DP55KG-400, Dual-channel SS Crucial 2GB (2x1GB) DDR3-1333 9-9-9-24 1T with 1x GF 9600GT PCIe graphics + Seagate* 320GB NCQ SATA2 (BIOS: 2429, INF:9.1.1.1014, Graphics: NV180.48, IMON compliant with VRD 11.1 requirements)



Configuration 2: Intel® Core™ i7-860 processor (2.80GHz, 4C/8T, 8MB Cache, IMC, DDR3-1333) on Intel® DP55KG-400, Dual-channel SS Crucial 2GB (2x1GB) DDR3-1333 9-9-9-24 1T with 1x GF 9600GT PCIe graphics + Seagate* 320GB NCQ SATA2 (BIOS: 2429, INF:9.1.1.1014, Graphics: NV180.48, IMON compliant with VRD 11.1 requirements)



Configuration 3: Intel® Core™ i5-750 processor (2.66GHz, 4C/4T, 8MB Cache, IMC, DDR3-1333) on Intel® DP55KG-400, Dual-channel SS Crucial 2GB (2x1GB) DDR3-1333 9-9-9-24 1T with 1x GF 9600GT PCIe graphics + Seagate* 320GB NCQ SATA2 (BIOS: 2429, INF:9.1.1.1014, Graphics: NV180.48, IMON compliant with VRD 11.1 requirements)

Common Operating System for Configurations 1, 2 and 3: Windows* Vista* Ultimate 32bit.

Chassis for Configurations 1, 2 and 3: Antec NSK6580B

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Consumer Configurations



Configuration 4: Intel® Core™ i7-950 Processor (8MB Cache, 3.06GHz, 4.8GT/s Intel® QPI) Intel® Hyper-Threading Technology ON, Intel® Turbo Boost Technology ON on Intel® DX58SO X58 Tri-channel SS Samsung* 3GB (3x1GB) DDR3-1066 7-7-7-20 with 1x GF 9600GT PCIe graphics, Seagate* 320GB NCQ SATA2 (BIOS: 2786, INF:9.1.0.1007, Graphics: NV180.48) , Windows* Vista* Ultimate 32bit



Configuration 5: Intel® Core™ i7-920 Processor (8MB Cache, 2.66GHz, 4.8GT/s Intel® QPI) Intel® Hyper-Threading Technology ON, Intel® Turbo Boost Technology ON on Intel® DX58SO X58 Tri-channel SS Samsung* 3GB (3x1GB) DDR3-1066 7-7-7-20 with 1x GF 9600GT PCIe graphics, Seagate* 320GB NCQ SATA2 (BIOS: 2786, INF:9.1.0.1007, Graphics: NV180.48) Windows* Vista* Ultimate 32bit



Configuration 6: Intel® Core™2 Quad Processor Q9650 (12MB Cache, 3.00GHz, 1333MHz FSB) Intel® DQ45CB/DG45ID, Dual channel DS Micron* 2GB (2x1GB) DDR2-800 5-5-5-18 with Integrated Intel® GMA X4500HD onboard graphics subsystem, Seagate* 320GB Barracuda* NCQ Serial ATA, (BIOS:0059, Intel Chipset INF: 9.0.0.1007, Graphics: 15.9.9.1527), Windows* Vista* Ultimate 32bit.



Configuration 7: Intel® Core™2 Quad Processor Q9550 (12MB Cache, 2.83GHz, 1333MHz FSB) Intel® DQ45CB/DG45ID, Dual channel DS Micron* 2GB (2x1GB) DDR2-800 5-5-5-18 with Integrated Intel® GMA X4500HD onboard graphics subsystem, Seagate* 320GB Barracuda* NCQ Serial ATA, (BIOS:0059, Intel Chipset INF: 9.0.0.1007, Graphics: 15.9.9.1527), Windows* Vista* Ultimate 32bit.



Configuration 8: Intel® Core™2 Quad Processor Q9400 (6MB Cache, 2.66GHz, 1333MHz FSB) Intel® DQ45CB/DG45ID, Dual channel DS Micron* 2GB (2x1GB) DDR2-800 5-5-5-18 with Integrated Intel® GMA X4500HD onboard graphics subsystem, Seagate* 320GB Barracuda* NCQ Serial ATA, (BIOS:0059, Intel Chipset INF: 9.0.0.1007, Graphics: 15.9.9.1527), Windows* Vista* Ultimate 32bit.

Gaming System Configurations



Configuration 9: Intel® Core™ i7-870 processor (2.93GHz, 4C/8T, 8MB Cache, IMC, DDR3-1333) on Intel® DP55KG-400, Dual-channel SS Crucial 2GB (2x1GB) DDR3-1333 9-9-9-24 1T with 1x GTX 280 PCIe graphics + Intel® 80GB X25-M SSD SATA2 (BIOS: 2429, INF:9.1.1.1014, Graphics: NV180.48, IMON compliant with VRD 11.1 requirements)



Configuration 10: Intel® Core™2 Quad Processor Q9650 (12MB Cache, 3.00GHz, 1333MHz FSB) on Asus* P5E3 Premium X48 chipset, Dual-channel Corsair CM3X1024-1333C9DHX 2GB (2x1GB) 9-9-9-24-1T with 1x GTX 280 PCIe graphics + Intel® 80GB X25-M SS D SATA2 (BIOS: 0505, INF:8.4.0.1016, Graphics:NV177.41), Windows* Vista* Ultimate 32bit.

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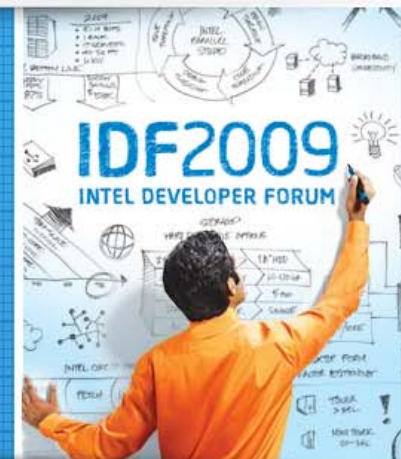
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